



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

EXAMINER: N. PAREKH

Art Unit 2811

APPLICANT: PETER ELENUS, ET AL.

SERIAL NO.: 09/575,298

FILED: May 19, 2000

FOR: "SOLDER BAR FOR HIGH POWER
FLIP CHIPS"

RECEIVED
OCT 30 2002
TECHNOLOGY CENTER 2800
12/B
11-2302
FJONES

Express Mail Mailing Label No. EL 816743855 US
Date of Deposit: October 24, 2002

I hereby certify that this paper or fee is being deposited with
the United States Postal Service "Express Mail Post Office to
Addressee" service under 37 CFR §1.10 on the date indicated
above and is addressed to BOX CPA, Commissioner for
Patents, Washington, D.C. 20231.

Marvin A. Glazer
Marvin A. Glazer

October 24 2002
Date

AMENDMENT

BOX CPA
Honorable Commissioner for Patents
Washington, D.C. 20231

Sir:

IN THE CLAIMS:

Please amend claim 16 as follows:

Sub B-1
16. A reflowable solder bar formed upon an upper surface of a first substrate, the first substrate having a first electrical contact, said reflowable solder bar being adapted to join the first electrical contact to a second electrical contact on a second substrate, said reflowable solder bar comprising in combination:

a. a first generally circular solder pad formed upon the upper surface of the first substrate, the first generally circular solder pad having a center, and having a first predetermined diameter D;